

a third semiconductor layer of said second conductivity type higher in an impurity concentration and thinner than said second semiconductor layer, and provided on a surface of said second semiconductor layer;

a fourth semiconductor layer of said first conductivity type provided on a surface of said third semiconductor layer, wherein said third semiconductor layer is interposed between said second semiconductor layer and a bottom of said fourth semiconductor layer and is in direct contact with said second semiconductor layer;

a fifth semiconductor layer of the second conductivity type selectively provided in a surface of said fourth semiconductor layer and opposing said third semiconductor layer through said fourth semiconductor layer;

a first main electrode disposed across and connected with surfaces of said fourth and fifth semiconductor layers;

a second main electrode provided on said second main surface of said first semiconductor layer;

an insulating film provided on a portion of said fourth semiconductor layer interposed between said third and fifth semiconductor layers; and

a control electrode facing said portion through said insulating film so that said portion forms a channel region.

REMARKS

Favorable reconsideration of this application, in view of the following comments and as presently amended, is respectfully requested.

Claims 22-39 are pending in this application. Claims 27-39 are withdrawn from consideration. Claims 22, 24, and 26 were rejected under 35 U.S.C. §102(b) as clearly